

KESTER® NP505-LT SOLDER PASTE

Lead-Free, No-Clean, Low Temperature Application Paste

DESCRIPTION

Kester NP505-LT Solder Paste is a no-clean, lead-free, zero-halogen solder paste for assemblies that have temperature sensitive substrates and components. Warpage is becoming more evident with the trend towards complex boards and the trend of using thinner and larger packages and boards. The defects caused by the warpage may decrease board reliability and increase in rework. NP505-LT is designed to reduce warpage inherent to board-to-package.

READ ENTIRE TECHNICAL DATA SHEET BEFORE USING THIS PRODUCT

FEATURES & BENEFITS

- Classified ROL0 per IPC J-STD-004B
- Zero-Halogen (none intentionally added)
- Low reflow peak temperatures (175 to 215 °C)
- Reduced reflow temperatures improving efficiency in energy and cost
- Reduction in board-to-package warpage
- Low voiding potential under QFNs (< 15%)
- Wide reflow profile window with good solderability on various PCB surface finish
- Excellent activity and printability
- Extremely stable paste properties
- Colorless residues for easy post-reflow inspection

ROHS COMPLIANCE

This product meets the requirements of the Restriction of Hazardous Substances (RoHS) Directive.

Category	Results	Procedure/Remarks
Physical Properties (Typical Values for Sn42Bi57Ag01, T4)		
Viscosity (Typical)	1400 poise	J-STD-004B, IPC-TM-650, Method 2.3.32D
Initial Tackiness (Typical)	40 grams	J-STD-005, IPC-TM-650, Method 2.4.44

Category	Results	Procedure/Remarks
Cold Slump Test	Pass	J-STD-005, IPC-TM-650, Method 2.4.35
Hot Slump Test	Pass	J-STD-005, IPC-TM-650, Method 2.4.35
Solder Ball Test	Pass	J-STD-005, IPC-TM-650, Method 2.4.43
Wetting	Pass	J-STD-005, IPC-TM-650, Method 2.4.45
Reliability Properties		
Copper Mirror	Low	J-STD-004B, IPC-TM-650, Method 2.3.32
Corrosion Corrosion	Low	J-STD-004B, IPC-TM-650, Method 2.6.15
Halogen Content	None Detected	Tested to J-STD-004B, IPC-TM-650, Method 2.3.81
Electrochemical Migration (ECM)	Pass	J-STD-004B, IPC-TM-650, Method 2.6.14.1 Test Conditions: 65 °C, 85% RH, 25 days, 100V
Surface Insulation Resistant (SIR)	Pass	J-STD-004B, IPC-TM-650, Method 2.6.3.7 Test Conditions: 40 °C, 90% RH, 7 days, 12.5V

PROCESS GUIDELINES

Below information are process guidelines, and it is advisable to note that the optimum setting for a given assembly may vary and this is dependent on the circuit board design, board thickness, components used and equipment used. A design of experiments is recommended to be done to optimize the soldering process.

Printing Process Parameters	Recommendations
Solder Paste Bead Size	Initial 2 cm (0.75 in); Add below 1.4 cm (0.5 in)
Squeegee Angle	60 deg. from horizontal

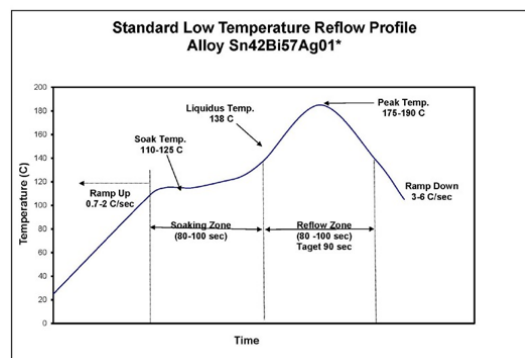
Speed	25 to 150 mm/sec (1 to 6 in/sec)
Pressure ¹	0.7 to 1.3 Kg/50mm (0.78 to 1.45 lb/in)
Separation Speed	≥ 5 to ≤ 20 mm/sec
Underside Cleaning ²	Solvent, vacuum, and dry wipe recommended
Stencil Life	12 hours at 20 to 25 °C (68 to 77 °F) / 30 to 60% RH

¹ Pressure should be increased with increasing print speed. First set the print speed. Then set the pressure to the minimum required to clean the solder paste off of the stencil.

² Some cleaning chemistry can interact with the solder paste and can impact the print performance.

In addition, incoming solderability inspection of circuit boards and components is recommended as part of process control to maintain consistent soldering performance and electrical reliability.

Recommended Reflow Profile



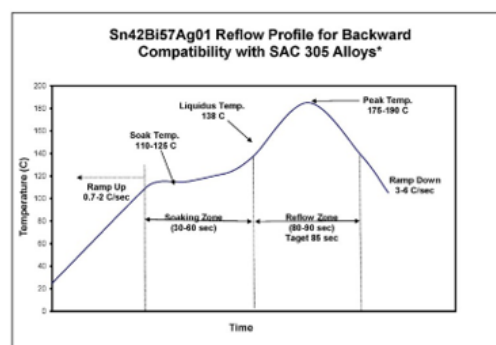
The general recommended convection reflow profile for the NP505-LT formula made with Sn42Bi57Ag01 is shown here as a starting point. Your final profile will depend on your board mass and component combination. NP505-LT has excellent solderability and wetting capabilities in air or nitrogen reflow atmospheres reflow equipment. Your optimal profile may be different from the basic graph. Please contact Kester Technical Support if you need profiling advice.

Reflow Process Parameter	Recommendations
Ramp Rate	0.7 to 2.0 °C/sec
Soak Temperature	110 to 125 °C
Soak Time	80 to 100 sec
Peak Temperature	175 to 190 °C
Time Above Liquidus	80 to 100 sec (target 90 sec)
Cooling Rate	3 to 6 °C/sec

Reflow Profile for Backward Compatibility with Sac305 Alloy*

Reflow Process Parameter	Recommendations
Ramp Rate	0.7 to 2.0 °C/sec
Soak Temperature	110 to 125 °C
Soak Time	30 to 60 sec
Peak Temperature	175 to 190 °C
Time Above Liquidus	80 to 90 sec (target 85 sec)
Cooling Rate	3 to 6 °C/sec

* This profile is simply a guideline. The mixing level between the Sn42Bi57Ag01 and SAC305 alloy is a function of reflow peak temperature, time above liquidus, component size and sphere alloy. Your optimal reflow profile may be different from the one shown based on your oven, component sphere size, sphere alloy and printed solder paste volume.



Cleaning

NP505-LT residues are non-conductive, non-corrosive, and do not require removal. If it is desired to remove the residues, commercially available residue cleaner may be used. Contact Kester Technical Support for additional assistance.

Storage, Handling and Shelf Life

Refrigeration (0 to 10 °C/32 to 50 °F) is the recommended storage condition for solder paste to maintain consistent viscosity, reflow characteristics and overall performance. Shelf life is 6 months from date of manufacture when refrigerated. NP505-LT should be stabilized at room temperature prior to printing. Please contact Kester Technical Support if you require additional advice with regards to handling and storage of this material.

AVAILABILITY

NP505-LT is available in Sn42Bi57Ag01 alloy with type 4 powder mesh (20 to 38µm). Type 4 mesh size is recommended for standard and fine pitch applications. NP505-LT standard packaging in 500gm jars and 600gm cartridges. The appropriate combination depends on the process variables and the specific application. If other packaging configuration is needed, please contact your Kester representative for additional information.

RECYCLING SERVICES

We provide safe and efficient recycling services to help companies meet their environmental and legislative requirements and at the same time, maximize the value of their waste streams.

Our service collects solder dross, solder scrap, and various forms of solder paste waste. Please contact your local sales representative for recycling capabilities in your area.



SAFETY & WARNING

It is recommended that the company/operator read and review the Safety Data Sheets for the appropriate health and safety warnings before use. **Safety Data Sheets are available.**

CONTACT INFORMATION

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Also read carefully warning and safety information on the Safety Data Sheet. This data sheet contains technical information required for safe and economical operation of this product. READ IT THOROUGHLY PRIOR TO PRODUCT USE. Emergency safety directory assistance: US 1 202 464 2554, Europe + 44 1235 239 670, Asia + 65 3158 1074, Brazil 0800 707 7022 and 0800 172 020, Mexico 01800 002 1400 and (55) 5559 1588

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